

ABSTRACT OF THE DISCLOSURE

The semiconductor device embraces a module substrate; a plurality of substrate-cite interconnects disposed on the first main surface of the module substrate; a semiconductor chip mounted with the flip chip configuration; a plurality of joints connected to the substrate-cite interconnects; a circuit board; a plurality of board-cite interconnects disposed on the top surface of the circuit board, each being connected to one of the joints; and a first heat conductive material thermally connecting the bottom surface of the semiconductor chip with the top surface of the circuit board.

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